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Pascal Oberndorff holds a Master and Ph.D. degree from the department of Chemical Engineering of the Eindhoven University of Technology, the Netherlands. He joined Philips Development Laboratories in 2001 as a materials scientist. In 2005 he switched to Package Innovation at Philips Semiconductors/NXP, where his initial responsibility was the introduction of Pb-free technology and eventually team-lead for the packaging materials team. In 2010 he returned to Philips, working on LED development and packaging for LED lighting at the Lighting division. In 2014 he rejoined NXP Package Innovation, where he was responsible for new product introduction in packaging for automotive industry until 2023. Since 2023 he is responsible for the Packaging Core Technology department within Package Innovation. This world-wide department encompasses materials, (thermo-mechanical/thermal) modeling, platform management and technology scouting of Electronic Packaging. He has (co-) authored around 30 publications and conference contribution about Pb-free introduction, materials technology, package development in automotive technology.